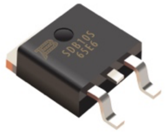
MATERIAL DECLARATION SHEET

BOURNS®

Material Number	BSDB10S65E6 TO263			
Product Line	Semiconductor			
Compliance Date	2023-05-22			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Die	Silicon Carbide	1.74	Silicon Carbide (SiC)	409-21-2	100	0.105	0.105
2	Die Attach	Die Attach	0.06	Diethylene Glycol Monoethyl Ether Acetate	112-15-2	5	0.004	0.066
			1.02	Silver (Ag)	7440-22-4	95	0.062	
3	Lead Frame	Copper alloy	0.22	Phosphorous (P)	7723-14-0	0.03	0.013	43.264
			0.22	Nickel (Ni)	7440-02-0	0.03	0.013	
			0.72	Iron (Fe)	7439-89-6	0.1	0.043	
			715.85	Copper (Cu)	7440-50-8	99.84	43.195	
4	Mold Compound	Resin	34.58	Phenol Formaldehyde resin (generic)	9003-35-4	3.8	2.087	54.911
			54.6	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6	3.295	
			819	Silica fused	60676-86-0	90	49.419	
			1.82	Carbon black	1333-86-4	0.2	0.11	
5	Plating	Tin plating	25	Tin (Sn)	7440-31-5	100	1.509	1.509
6	Wire	Pure metal	2.42	Aluminium (Al)	7429-90-5	100	0.146	0.146
		Total weight	1657.25 mg					

This Document was updated on: 2023/05/22

(EU) RoHS Directive 2011/65/EU ANNEX Application of lead which are exempted from the requirements